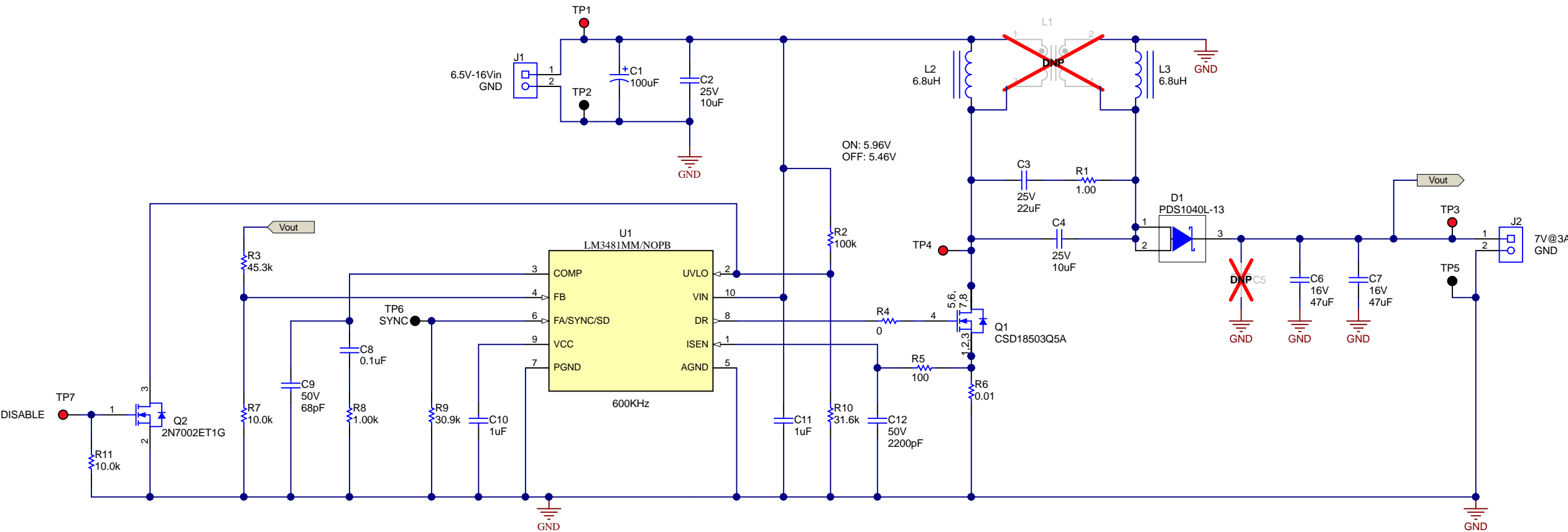


NOTES:
1) Ref Des' match PMP20175 REVA PCB.



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Orderable: N/A	Designed for: Public Release	Mod. Date: 8/25/2017
TID #:	Project Title: LM3481 SEPIC 7V@3A	
Number: PMP20175	Rev: C	Sheet: 1 of 1
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B
Drawn By:	File: PMP20175 REVC.SchDoc	
Engineer: J Betten	Contact: http://www.ti.com/support	

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